

**Amendments to the Specification**

Please replace the paragraph beginning at page 15, line 8, with the following rewritten paragraph:

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B1 With reference to FIG. 7, in a fourth embodiment of the invention, a processor board 401 carrying a plurality of heat-producing components 403 of potentially different heights includes an entirely self-contained system for connection to a liquid loop, including a pump 404 and a heat exchanger 406.

10 Similar to the third embodiment, the processor board includes a layer of thermally conductive material 405 (i.e., a thermal interface) at least partially encapsulating heat-producing components on each side of the board having such components. The layer of thermally conductive material is of a relatively thermally conductive material such as metal (having excellent thermal conductivity) or thermally  
15 conductive foam (typically being more economical to use). The layer can be machined to shape and attached by adhesion or structural support. Alternatively, the layer can be formed by applying a liquid/not-yet-solidified foam, and having it solidify.